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WIRELESS USB PROMOTER GROUP MEMBERSHIP TOPS 85 COMPANIES

Ecosystem Support Increases; Demo at International CES

PORTLAND, Ore., January 3, 2005 – The Wireless USB Promoter Group, formed in February 2004 to define the first standard for high speed wireless personal connectivity, reached a membership milestone by gaining more than 85 member companies since soliciting contributors to the Wireless USB (WUSB) specification definition in November 2004.

Intel Corporation, Philips Electronics and Staccato Communications, will demo the latest WUSB technology at International CES, January 6-9 in Las Vegas. The demo provides additional proof points of WUSB and MultiBand OFDM-based UWB technology targeted for PCs and PC peripherals, consumer electronics and mobile devices applications.

Wireless USB personal connectivity will bring the convenience and mobility of wireless communications to high-speed interconnects for multimedia consumer electronics, PC peripherals and mobile devices. With a targeted bandwidth of 480 Mbps, WUSB will feature wireless high-data throughput with low power consumption for distances less than 10 meters. The WUSB interface will deliver the benefits of high-speed wireless connectivity, increased security, ease-of-use and backward compatibility to customers.

The WUSB Promoter Group will also show the NEC Electronics Device Wire Adapter (DWA). The DWA allows a wired USB device to communicate with a Wireless USB host.

About Wireless USB

The WUSB Promoter Group, consisting of Agere Systems, HP, Intel, Microsoft, NEC, Philips Electronics and Samsung, is committed to preserving the existing USB devices, class driver infrastructure and investment, look-and-feel and ease-of-use of wired USB. WUSB will

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maintain the same scalable device performance and capability while also addressing new consumer electronics requirements.

The first Wireless USB implementations will be in the form of discrete silicon that will be introduced in a number of form factors. These include add-in cards and dongles along with embedded solutions to support the technology's introduction and subsequent rapid ramp-up.

New contributor members are welcome to join this group. For more information, visit www.usb.org/wusb.